

TIC106A, TIC106B, TIC106C, TIC106D, TIC106E, TIC106M, TIC106N, TIC106S

P-N-P-N SILICON REVERSE-BLOCKING TRIODE THYRISTORS

- 5 A Continuous On-State Current
- 30 A Surge-Current
- Glass Passivated Wafer
- 100 V to 800 V Off-State Voltage
- Max I_{GT} of 200 μA
- Compliance to ROHS

ABSOLUTE MAXIMUM RATINGS

Symbol	Ratings	Value								Unit
		Α	В	С	D	Е	M	S	N	Jiiit
V _{DRM}	Repetitive peak off-state voltage (see Note1)	100	200	300	400	500	600	700	800	V
V _{RRM}	Repetitive peak reverse voltage	100	200	300	400	500	600	700	800	٧
I _{T(RMS)}	Continuous on-state current at (or below) 80°C case temperature (see note2)	5						Α		
I _{T(AV)}	Average on-state current (180° conduction angle) at(or below) 80°C case temperature (see Note3)	3.2					Α			
I _{TM}	Surge on-state current (see Note4)	30					Α			
I _{GM}	Peak positive gate current (pulse width ≤300 µs)	0.2						Α		
P _{GM}	Peak power dissipation (pulse width ≤300 µs)	1.3					W			
P _{G(AV)}	Average gate power dissipation (see Note5)	0.3					W			
T _C	Operating case temperature range	-40 to +110					°C			
T _{stg}	Storage temperature range	-40 to +125					°C			
TL	Lead temperature 1.6 mm from case for 10 seconds	230				°C				



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THERMAL CHARACTERISTICS

Symbol	Ratings	Value	Unit		
t _{gt}	Gate-controlled Turn-on time	V_{AA} = 30 V, R_L = 6 Ω $R_{GK(eff)}$ = 5 k Ω V_{in} = 50 V	1.75	su Su	
tq	Circuit-communicated Turn-off time	$V_{AA} = 30 \text{ V}, R_L = 6 \Omega$ $I_{RM} \approx 8 \text{ A}$	7.7	·	
R _{∂JC}	Junction to case thermal resistance	≤ 3.5	°C/W		
R _{∂JA}	Junction to free air thermal resistance		≤ 62.5	C/VV	

ELECTRICAL CHARACTERISTICS

TC=25°C unless otherwise noted

Symbol	Ratings	Test Condition(s)	Min	Тур	Max	Unit
I _{DRM}	Repetitive peak off-state current	V_D = Rated V_{DRM} R_{GK} = 1 k Ω , T_C = 110°C	-	-	400	μΑ
I _{RRM}	Repetitive peak reverse current	V_R = Rated V_{RRM} , I_G = 0 T_C = 110°C	-	-	1	mA
I _{GT}	Gate trigger current	V_{AA} = 6 V, R _L = 100 Ω $t_{p(g)} \ge 20 \mu s$	-	60	200	μA
		V_{AA} = 6 V, R _L = 100 Ω R _{GK} = 1 kΩ, t _{p(g)} ≥ 20μs T _C = -40°C	-	-	1.2	
V_{GT}	Gate trigger voltage	V_{AA} = 6 V, R _L = 100 Ω R _{GK} = 1 kΩ, t _{p(q)} ≥ 20μs	0.4	0.6	1	V
		V_{AA} = 6 V, R _L = 100 Ω R _{GK} = 1 kΩ, t _{p(g)} ≥ 20μs T _C = 110°C	0.2	-	-	
I _H	Holding current	$V_{AA} = 6 \text{ V}, R_{GK} = 1 \text{ k}\Omega$ initiating $I_T = 10 \text{ mA}$	-	-	5	
		V_{AA} = 6 V, R_{GK} = 1 kΩ initiating I_T = 10 mA T_C = -40°C	-	-	8	mA
V _{TM}	Peak on-state voltage	I _{TM} = 5A (see Note6)	-	-	1.7	V
dv/dt	Critical rate of rise of off-state voltage	V_D = Rated V_D R_{GK} = 1 k Ω , T_C = 110°C	-	10	-	V/µs



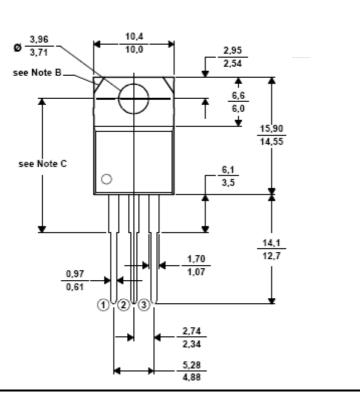
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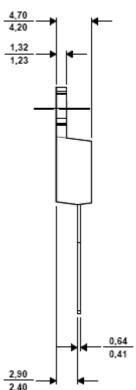
Notes:

- 1. These values apply when the gate-cathode resistance R_{GK} = $1k\Omega$
- 2. These values apply for continuous dc operation with resistive load. Above 80°C derate linearly to zero at 110°C.
- 3. This value may be applied continuously under single phase 50 Hz half-sine-wave operation with resistive load. Above 80°C derate linearly to zero at 110°C.
- 4. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
- 5. This value applies for a maximum averaging time of 20 ms.
 6. This parameters must be measured using pulse techniques, t_W = 300µs, duty cycle ≤ 2 %, voltagesensing contacts, separate from the courrent-carrying contacts, are located within 3.2mm (1/8 inch) from de device body.

MECHANICAL DATA CASE TO-220



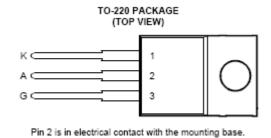






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PINNING



Pin 1 :	kathode
Pin 2 :	Anode
Pin 3 :	Gate

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